2SB1179, 2SB1179A

Silicon PNP epitaxial planar type darlington

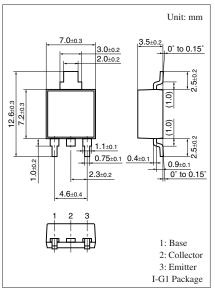
For power amplification and switching Complementary to 2SD1749, 2SD1749A

■ Features

- \bullet High forward current transfer ratio $h_{\mbox{\scriptsize FE}}$ which has satisfactory linearity
- High-speed switching
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment

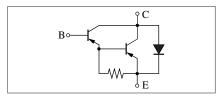
■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SB1179	V _{CBO}	-60	V
(Emitter open)	2SB1179A		-80	
Collector-emitter voltage	2SB1179	V _{CEO}	-60	V
(Base open)	2SB1179A		-80	
Emitter-base voltage (Col	V_{EBO}	-5	V	
Collector current	I_C	-4	A	
Peak collector current	I_{CP}	-8	A	
Collector power dissipation	P _C	15	W	
	$T_a = 25$ °C		1.3	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Note) Self-supported type package is also prepared.

Internal Connection

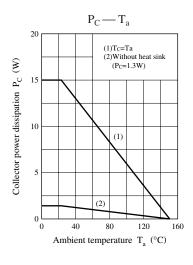


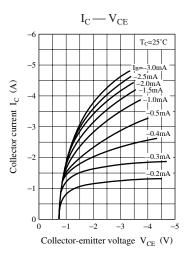
■ Electrical Characteristics $T_C = 25$ °C ± 3 °C

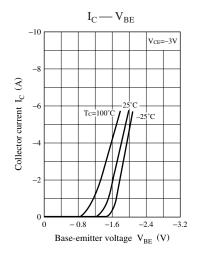
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SB1179	V _{CEO}	$I_C = -30 \text{ mA}, I_B = 0$	-60			V
(Base open)	2SB1179A			-80			
Base-emitter voltage		V_{BE}	$V_{CE} = -3 \text{ V}, I_{C} = -3 \text{ A}$			-2.5	V
Collector-base cutoff	2SB1179	I_{CBO}	$V_{CB} = -60 \text{ V}, I_{E} = 0$			-200	μΑ
current (Emitter open)	2SB1179A		$V_{CB} = -80 \text{ V}, I_{E} = 0$			-200	
Collector-emitter cutoff	2SB1179	I_{CEO}	$V_{CE} = -40 \text{ V}, I_{B} = 0$			-500	μΑ
current (Base open)	2SB1179A		$V_{CE} = -40 \text{ V}, I_{B} = 0$			-500	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = -5 \text{ V}, I_{C} = 0$			-2	mA
Forward current transfer ratio		h _{FE1}	$V_{CE} = -3 \text{ V}, I_{C} = -0.5 \text{ A}$	1000			_
		h _{FE2} *	$V_{CE} = -3 \text{ V}, I_{C} = -3 \text{ A}$	2000		10 000	
Collector-emitter saturation voltage		V _{CE(sat)}	$I_C = -3 \text{ A}, I_B = -12 \text{ mA}$			-2	V
			$I_C = -5 \text{ A}, I_B = -20 \text{ mA}$			-4	
Transition frequency		f_T	$V_{CE} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time		t _{on}	$I_C = -3 \text{ A}, I_{B1} = -12 \text{ mA}, I_{B2} = 12 \text{ mA}$		0.3		μs
Storage time		t _{stg}	$V_{CC} = -50 \text{ V}$		2.0		μs
Fall time		$t_{\rm f}$			0.5		μs

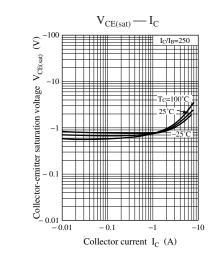
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

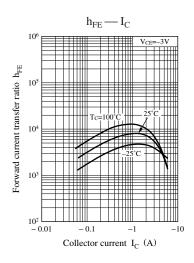
2. *: Rank classification	Rank	Q	Р
	h _{FE2}	2000 to 5000	4000 to 10000

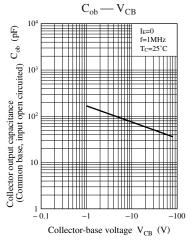


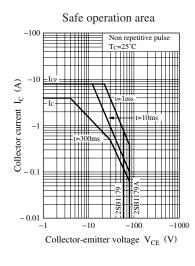


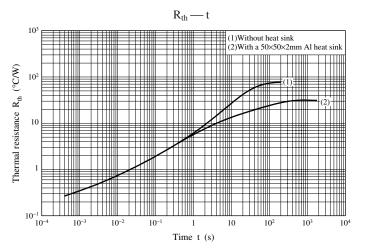












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